

PROPOSED CLAIM AMENDMENT

1. A flip chip package comprising:

a semiconductor chip having a first side and a second side opposing the first side;
a circuit substrate electrically connected to the first side of the semiconductor chip;
a protective cap disposed over the second side of the semiconductor chip, the protective cap including at least one portion extending beyond an edge of the semiconductor chip, the portion including a groove have a fan-shaped cross-section such that a part of the groove further from the second side of the semiconductor chip is wider in cross-section than a part of the groove closer to the second side of the semiconductor chip; and
a molding resin layer sealing the electrical connection between the semiconductor chip and the circuit substrate and filling the fan-shaped groove in the cap; and
an adhesion layer disposed between the second side of the semiconductor chip and the protective cap.